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2. (Amended) The display of claim [1] 17, wherein said [at least one cut surface] side edge of said TFT substrate to which said nonconductive or weakly conductive material is applied or adhesively bonded is parallel or vertical to a direction of array of said pixel TFTs.

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4. (Amended) The display of claim [1] 17, wherein in order to install [a] said control circuit [for controlling said driver circuit made up of said driver TFTs] in a control circuit accommodation portion ~~of~~ said TFT substrate, said control circuit accommodation portion is made thinner than other portions of said TFT substrate.

5. (Amended) The display of claim [1] 17, wherein in order to install [a] said control circuit [for controlling said driver circuit made up of said driver TFTs] in a control circuit accommodation portion of said ~~TFT~~ substrate, said counter substrate has a thinned portion located opposite to said control circuit accommodation portion. 112

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6. (Amended) The display of claim [3] 17, wherein said control circuit is packed [on] over said TFT substrate by COG (chip-on-glass) technology.

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10. (Amended) The method of claim [9] 24, wherein said cutting step is carried out in such a way that said cut end

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surfaces to which said nonconductive or weakly conductive material is applied or adhesively bonded are parallel or vertical to a direction of array of said pixel TFTs.

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12. (Amended) The method of claim [9] 24, further comprising the step of thinning a region of said TFT substrate where a control circuit for controlling said driver circuit made up of said driver TFTs *can* be installed, in order to install said control circuit.

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13. (Amended) The method of claim [9] 24, further comprising the step of thinning a portion of said counter substrate which is located opposite to a control circuit for controlling said driver circuit made up of said driver TFTs, to install said control circuit.

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14. (Amended) The method of claim [11] 24, wherein said control circuit is packed [on] over said TFT substrate by COG (chip-on-glass) technology.

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17. (Amended) An active matrix liquid crystal display comprising:

a plurality of pixel TFTs arranged in rows and columns [on] over a TFT substrate and arrayed in a matrix;

driver TFTs formed [on] over said TFT substrate and forming a driver circuit for driving said pixel TFTs;

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a layer of a liquid crystal material with which said pixel TFTs and driver TFTs are in contact directly or via a thin film; a counter substrate located opposite to said TFT substrate; [a bus line provided on said TFT substrate and connected with corresponding pixel TFTs; and]

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a nonconductive or weakly conductive material applied or adhesively bonded to a side edge of said counter substrate and a side edge of said TFT substrate [and a part of said bus line provided at said side edge of said TFT substrate,];

a sealing material provided between said TFT substrate and said counter substrate and inside said side edge of said counter substrate and said side edge of said TFT substrate; and

a control circuit provided within and in contact with said sealing material

[wherein said nonconductive or weakly conductive material is provided outside a control circuit for controlling said driver circuit or outside said bus line].

Please add new claims 21-44 as follows:

--21. (New) An active matrix liquid crystal display comprising:

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a plurality of pixel TFTs arranged in rows and columns over a TFT substrate and arrayed in a matrix;

a driver TFTs formed over said TFT substrate and forming a

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driver circuit for driving said pixel TFTs;

a layer of a liquid crystal material with which said pixel TFTs and driver TFTs are in contact directly or via a thin film;

a counter substrate located opposite to said TFT substrate;

a nonconductive or weakly conductive material applied or adhesively bonded to a side edge of said counter substrate and a side edge of said TFT substrate;

a sealing material provided between said TFT substrate and said counter substrate and inside said side edge of said counter substrate and said side edge of said TFT substrate; and

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a control circuit provided within and in contact with said sealing material for controlling said driver circuit.

22. (New) An active matrix liquid crystal display comprising:

a plurality of pixel TFTs arranged in rows and columns over a TFT substrate and arrayed in a matrix;

driver TFTs formed over said TFT substrate and forming a driver circuit for driving said pixel TFTs;

a layer of a liquid crystal material with which said pixel TFTs and driver TFTs are in contact directly or via a thin film;

a counter substrate located opposite to said TFT substrate;

a nonconductive or weakly conductive material applied or adhesively bonded to a side edge of said counter substrate and a

side edge of said TFT substrate;

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a sealing material provided between said TFT substrate and said counter substrate and inside said side edge of said counter substrate and said side edge of said TFT substrate, said sealing material being provided outside at least said pixel TFTs; and

a control circuit provided within and in contact with said sealing material for controlling said driver circuit. Fig 4

23. (New) An active matrix liquid crystal display comprising:

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a plurality of pixel TFTs arranged in rows and columns over a TFT substrate and arrayed in a matrix;

driver TFTs formed over said TFT substrate and forming a driver circuit for driving said pixel TFTs;

a layer of a liquid crystal material with which said pixel TFTs and driver TFTs are in contact directly or via a thin film;

a counter substrate located opposite to said TFT substrate;

a nonconductive or weakly conductive material applied or adhesively bonded to a side edge of said counter substrate and a side edge of said TFT substrate;

a sealing material provided between said TFT substrate and said counter substrate and inside said side edge of said counter substrate and said side edge of said TFT substrate, said sealing material being provided outside said pixel TFTs and said driver

TFTs; and

a control circuit provided within and in contact with said sealing material for controlling said driver circuit.

24. (New) A method of fabricating an active matrix liquid crystal display comprising:

a plurality of pixel TFTs arranged in rows and columns over a TFT substrate and arrayed in a matrix;

driver TFTs formed over said TFT substrate and forming a driver circuit for driving said pixel TFTs;

a layer of a liquid crystal material with which said pixel TFTs and driver TFTs are in contact directly or via a thin film;

a counter substrate located opposite to said TFT substrate;

a sealing material provided between said TFT substrate and said counter substrate and outside at least said pixel TFTs; and

a control circuit provided within and in contact with said sealing material for controlling said driver circuit,

said method comprising:

cutting said TFT substrate and said counter substrate outside said sealing material having said control circuit within and in contact with said sealing material; and

applying or adhesively bonding a nonconductive or weakly conductive material to the cut side edge of said TFT substrate and the cut side edge of said counter substrate.

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25. (New) A method of fabricating an active matrix liquid crystal display comprising:

a plurality of pixel TFTs arranged in rows and columns over a TFT substrate and arrayed in a matrix;

driver TFTs formed over said TFT substrate and forming a driver circuit for driving said pixel TFTs;

a layer of a liquid crystal material with which said pixel TFTs and driver TFTs are in contact directly or via a thin film;

a counter substrate located opposite to said TFT substrate;

a sealing material provided between said TFT substrate and said counter substrate and outside said pixel TFTs and said driver TFTs; and

a control circuit provided within and in contact with said sealing material for controlling said driver circuit,

said method comprising:

cutting said TFT substrate and said counter substrate outside said sealing material having said control circuit within and in contact with said sealing material; and

applying or adhesively bonding a conductive or weakly conductive material to the cut side edge of said TFT substrate and the cut side edge of said counter substrate.

26. (New) The display of claim 17, wherein said sealing material seals said liquid crystal material.

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27. (New) The display of claim 21, wherein said side edge of said TFT substrate to which said nonconductive or weakly conductive material is applied or adhesively bonded is parallel or vertical to a direction of array of said pixel TFTs.

28. (New) The display of claim 21, wherein said sealing material seals said liquid crystal material.

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29. (New) The display of claim 21, wherein in order to install said control circuit in a control circuit accommodation portion of said TFT substrate, said control circuit accommodation portion is made thinner than other portions of said TFT substrate.

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30. (New) The display of claim 21, wherein in order to install said control circuit in a control circuit accommodation portion of said TFT substrate, said counter substrate has a thinned portion located opposite to said control circuit accommodation portion.

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31. (New) The display of claim 21, wherein said control circuit is packed over said TFT substrate by COG (chip-on-glass) technology.

32. (New) The display of claim 22, wherein said side edge of said TFT substrate to which said nonconductive or weakly



conductive material is applied or adhesively bonded is parallel or vertical to a direction of array of said pixel TFTs.

33. (New) The display of claim 22, wherein said sealing material seals said liquid crystal material.

1124 34. (New) The display of claim 22, wherein in order to install said control circuit in a control circuit accommodation portion of said TFT substrate, said control circuit accommodation portion is made thinner than other portions of said TFT substrate.

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35. (New) The display of claim 22, wherein in order to install said control circuit in a control circuit accommodation portion of said TFT substrate, said counter substrate has a thinned portion located opposite to said control circuit accommodation portion.

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36. (New) The display of claim 22, wherein said control circuit is packed over said TFT substrate by COG (chip-on-glass) technology.

37. (New) The display of claim 23, wherein said side edge of said TFT substrate to which said nonconductive or weakly conductive material is applied or adhesively bonded is parallel or vertical to a direction of array of said pixel TFTs.

38. (New) The display of claim 23, wherein said sealing material seals said liquid crystal material.

39. (New) The display of claim 23, wherein in order to install said control circuit in a control circuit accommodation portion of said TFT substrate, said control circuit accommodation portion is made thinner than other portions of said TFT substrate.

40. (New) The display of claim 23, wherein in order to install said control circuit in a control circuit accommodation portion of said TFT substrate, said counter substrate has a thinned portion located opposite to said control circuit accommodation portion.

41. (New) The display of claim 23, wherein said control circuit is packed over said TFT substrate by COG (chip-on-glass) technology.

42. (New) The method of claim 25, wherein said cutting step is carried out in such a way that said cut side edges to which said nonconductive or weakly conductive material is applied or adhesively bonded are parallel or vertical to a direction of array of said pixel TFTs.

43. (New) The method of claim 25, further comprising the step of thinning a region of said TFT substrate where said control circuit can be installed, in order to install said control circuit.

44. (New) The method of claim 25, further comprising the step of thinning a portion of said counter substrate which is located opposite to said control circuit, to install said control circuit.

45. (New) The display of claim 17, wherein said control circuit comprises a semiconductor chip.

46. (New) The display of claim 21, wherein said control circuit comprises a semiconductor chip.

47. (New) The display of claim 22, wherein said control circuit comprises a semiconductor chip.

48. (New) The display of claim 23, wherein said control circuit comprises a semiconductor chip.

49. (New) The method of claim 24, wherein said control circuit comprises a semiconductor chip.

50. (New) The method of claim 25, wherein said control circuit comprises a semiconductor chip.

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51. (New) The display of claim 17, wherein said sealing material is apart from said side edge of said counter substrate and said side edge of said TFT substrate.

52. (New) The display of claim 21, wherein said sealing material is apart from said side edge of said counter substrate and said side edge of said TFT substrate.

53. (New) The display of claim 22, wherein said sealing material is apart from said side edge of said counter substrate and said side edge of said TFT substrate.

54. (New) The display of claim 23, wherein said sealing material is apart from said side edge of said counter substrate and said side edge of said TFT substrate.

55. (New) The method of claim 24, wherein said sealing material is apart from said side edge of said counter substrate and said side edge of said TFT substrate.

56. (New) The method of claim 25, wherein said sealing material is apart from said side edge of said counter substrate and said side edge of said TFT substrate.

REMARKS